12 Aug	ust 200	4 Updated Search		09/868,577
L Number	Hits	Search Text	DB	Time stamp
-	1571	204/\$.ccls. and (wafer or semiconductor) and seal	USPAT;	2004/04/20
			US-PGPUB;	08:59
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	531	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	S.USPAT;	2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor)	US-PGPUB;	08:46
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	218	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc	SUSPAT;	2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	10:30
		and seal	EPO; JPO;	
			DERWENT;	
i			IBM_TDB	
_	60	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	_	2003/10/27
	]	204/224r,224m.ccls.) and sponge	US-PGPUB;	09:18
			EPO; JPO;	
			DERWENT,	
			IBM_TDB	
-	2	6176992.pn.	USPAT;	2003/10/27
		* '	US-PGPUB;	09:25
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	14	("3595089"   "4610772"   "5024735"   "5171412"	USPAT	2003/10/27
		"5429733"   "5558568"   "5692947"   "5755859"		09:26
		"5807165"   "5833820"   "5863412"   "5930669"		
ĺ		"5933753"   "6004880").PN.		
	2	6228233.pn.	USPAT;	2003/10/27
		·	US-PGPUB;	09:33
			EPO; JPO;	
			DERWENT;	
		•	IBM_TDB	
-	2	4807973.pn.	USPAT;	2003/10/27
		•	US-PGPUB;	09:33
		*	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	23	(204/\$.ccls. or 205/\$.ccls.) and datta.in.	USPAT;	2003/10/27
			US-PGPUB;	10:33
			EPO; JPO;	
	į		DERWENT;	
			IBM_TDB	
-	3838	204/198,232,237,242,275.1,297.01,297.06,297.14.ccls		2003/10/27
		204/224r,224m.ccls.	US-PGPUB;	10:53
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

-	313	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	S.USPAT;	2003/10/27
		204/224r,224m.ccls.) and (temperature with (anode	US-PGPUB;	10:54
	1	or cathode or electrode))	EPO; JPO;	
		<b>"</b>	DERWENT;	
			IBM_TDB	
-	67	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	S.USPAT;	2003/10/27
		204/224r,224m.ccls.) and (temperature near2 (anode	US-PGPUB;	11:03
		or cathode or electrode))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	- 00
-	10	3859196.URPN.	USPAT	2003/10/27 11:01
-	30	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	s.USPAT;	2003/10/27 11:13
		204/224r,224m.ccls.) and ((temperature near2	US-PGPUB;	
		control\$5) with (anode or cathode or electrode))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	("5507923"   "6017437").PN.	USPAT	2003/10/27
				11:06
-	25	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	s.USPAT;	2003/10/27 11:19
		204/224r,224m.ccls.) and ((coolant or (cooling adj	US-PGPUB;	
		(fluid or liquid))) with (anode or cathode or	EPO; JPO;	
		electrode))	DERWENT;	
			IBM_TDB	¥.
-	531	(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl	s.USPAT;	2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor)	US-PGPUB;	11:20
			EPO; JPO;	
			DERWENT;	
			IBW_TDB	
-	375	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc		2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	11:22
		and (coolant or (cooling fluid) or heat or heating)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	176	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc		2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	11:22
		and ((coolant or (cooling fluid) or heat or heating)	EPO; JPO;	
		with (anode or cahode or electrode))	DERWENT;	
		//204/109 222 227 242 275 4 227 24 227 24 227 1	IBM_TDB	2002/40/27/4/21
-	93	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc		2003/10/27 11:21
		204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	
		and ((coolant or (cooling fluid) or heat or heating)	EPO; JPO;	
		near3 (anode or cahode or electrode))	DERWENT;	
	9	//204/108 232 237 242 275 1 207 01 207 04 207 14	IBM_TDB	2002/10/27 11:21
-		((204/198,232,237,242,275.1,297.01,297.06,297.14.cc 204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	2003/10/27 11:21
		and ((coolant or (cooling adj fluid) or heat or heating)	EPO; JPO;	
		near3 (anode or cahode or electrode))	DERWENT;	
		near a famore of canoac of electrode))	IBM_TDB	
_	197	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc	_	2003/10/27
	''	204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	11:22
		and (coolant or (cooling adj fluid) or heat or heating)	EPO; JPO;	e d + tin tin
		and to the times and trained of the times	DERWENT;	
			IBM_TDB	
<u> </u>	ı			L

	1	//004/400 000 007 040 077 / 007 04 077		T
-	32	((204/198,232,237,242,275.1,297.01,297.06,297.14.cc	-	2003/10/27
		204/224r,224m.ccls.) and (wafer or semiconductor))	US-PGPUB;	11:22
		and ((coolant or (cooling adj fluid) or heat or heating)	EPO; JPO;	
		with (anode or cahode or electrode))	DERWENT;	
			IBM_TDB	
-	2	("5507923"   "6017437").PN.	USPAT	2003/10/27
				11:27
-	0	868577.apn.	USPAT;	2003/10/27
		·	US-PGPUB;	11:42
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
<u>-</u>	22	(US-6077412-\$ or US-6017437-\$ or US-5951833-\$	USPAT;	2003/10/27
		or US-5567300-\$ or US-5776330-\$ or	US-PGPUB	
		US-6176992-\$ or US-6228233-\$ or US-6251235-\$	03-76708	11:50
1	]	•		
		or US-6258240-\$ or US-6261433-\$ or		
	]	US-6270647-\$ or US-6328872-\$ or US-6334937-\$		
		or US-6103096-\$ or US-5284554-\$ or		
		US-3859196-\$ or US-6398926-\$ or US-5228966-\$		
İ		or US-5198083-\$ or US-3894925-\$ or		
		US-3637468-\$).did. or (US-20020056647-\$).did.		
-	8	((US-6077412-\$ or US-6017437-\$ or US-5951833-\$	USPAT;	2003/10/27 11:51
		or US-5567300-\$ or US-5776330-\$ or	US-PGPUB;	
		US-6176992-\$ or US-6228233-\$ or US-6251235-\$	EPO; JPO;	
		or US-6258240-\$ or US-6261433-\$ or	DERWENT;	
		US-6270647-\$ or US-6328872-\$ or US-6334937-\$	IBM_TDB	
		or US-6103096-\$ or US-5284554-\$ or	<del>-</del>	
		US-3859196-\$ or US-6398926-\$ or US-5228966-\$		
		or US-5198083-\$ or US-3894925-\$ or		]
	1	US-3637468-\$).did. or (US-20020056647-\$).did.)		
		and ((electrolyte or solution or fluid) with		
		(temperature or cool\$4 or heat\$4))		
_	7	((US-6077412-\$ or US-6017437-\$ or US-5951833-\$	USPAT;	2003/10/27
	•	or US-5567300-\$ or US-5776330-\$ or	US-PGPUB;	1
		US-6176992-\$ or US-6228233-\$ or US-6251235-\$	EPO; JPO;	12:32
		or US-6258240-\$ or US-6261433-\$ or		
			DERWENT;	
		US-6270647-\$ or US-6328872-\$ or US-6334937-\$	IBW_LDB	
		or US-6103096-\$ or US-5284554-\$ or		
]		US-3859196-\$ or US-6398926-\$ or US-5228966-\$		
[		or US-5198083-\$ or US-3894925-\$ or		
		US-3637468-\$).did. or (US-20020056647-\$).did.)		
		and (dc or (direct adj current))		
-	0	868577.apn.	USPAT;	2004/04/20
			US-PGPUB;	08:59
	İ		EPO; JPO;	
			DERWENT;	
	ł		IBM_TDB	
-	2655	204/198,232,237,242,275.1,297.01,297.06,297.14.ccls		2004/04/20
			US-PGPUB;	09:50
	ĺ		EPO; JPO;	=5.755
			DERWENT;	
			IBM_TDB	
<u> </u>				

-	68	204/198,232,237,242,275.1,297.01,297.06,297.14.ccls	LISPAT	2004/04/20
		and (ammeter or (current near (detect\$4 or sensor	US-PGPUB;	10:01
		or sense or sensing or sensed)))	EPO; JPO;	10.01
		or sense of sensing of senseappy	DERWENT;	
			IBM_TDB	
_	1521	204/224r,224m.ccls.	USPAT;	2004/04/20
		20 (7 = 2 11 / 2 11 11 11 11 11 11 11 11 11 11 11 11 1	US-PGPUB;	10:01
			EPO; JPO;	10.01
			DERWENT;	
			IBM_TDB	
_	47	204/224r,224m.ccls. and (ammeter or (current near	USPAT;	2004/04/20
		(detect\$4 or sensor or sense or sensing or sensed)))	US-PGPUB;	10:16
	İ	, and the same of same and a same and a same and a same a	EPO; JPO;	
			DERWENT;	
	1		IBM_TDB	
_	42	(204/224r,224m.ccls. and (ammeter or (current near	USPAT;	2004/04/20
		(detect\$4 or sensor or sense or sensing or sensed))))	US-PGPUB;	10:03
		not	EPO; JPO;	
		(204/198,232,237,242,275.1,297.01,297.06,297.14.ccl		
		and (ammeter or (current near (detect\$4 or sensor	IBM_TDB	
		or sense or sensing or sensed))))		
-	1686	205/118,122,125.ccls.	USPAT;	2004/04/20
			US-PGPUB;	10:04
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	17	205/118,122,125.ccls. and (ammeter or (current near	USPAT;	2004/04/20
		(detect\$4 or sensor or sense or sensing or sensed)))	US-PGPUB,	10:04
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	868577.apn.	USPAT;	2004/08/12
			US-PGPUB;	10:49
			EPO; JPO;	
			DERWENT;	
ļ l			IBM_TDB	
[ -	614	204/229.8.ccls. 205/775,790.5,791.5.ccls.	USPAT;	2004/08/12
1			US-PGPUB;	10:49
			EPO; JPO;	
			DERWENT;	
			IBW_LDB	
-	5	(204/229.8.ccls. 205/775,790.5,791.5.ccls.) and	USPAT;	2004/08/12 11:01
		(pinhole or (pin adj hole))	US-PGPUB;	i
			EPO; JPO;	
			DERWENT;	
			IBW_LDB	
-	18	4473795.URPN.	USPAT	2004/08/12
				10:52
	64	(204/229.8.ccls. 205/775,790.5,791.5.ccls.) and	USPAT;	2004/08/12
		(cavity or discontinuity)	US-PGPUB;	11:02
			EPO; JPO;	
		·	DERWENT;	
			IBM_TDB	

-	94	(204/229.8.ccls. 205/775,790.5,791.5.ccls.) and	USPAT;	2004/08/12
		(cavity or discontinuity or defect)	US-PGPUB;	11:02
			EPO; JPO;	
			DERWENT;	
			IBW_TDB	
-	12	(204/229.8.ccls. 205/775,790.5,791.5.ccls.) and	USPAT;	2004/08/12
	*	((cavity or discontinuity or defect) with current)	US-PGPUB;	11:03
		*	EPO; JPO;	
			DERWENT;	
			IBW_TDB	
-	4	("3373353"   "3772520"   "3792458"	USPAT	2004/08/12
		"4296372").PN.		11:25
-	10	3792458.URPN.	USPAT	2004/08/12
				11:26